

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A process for producing a ceramic sheet, which comprises molding a ceramic sheet having a thickness of from 1 to 10 mm by using an extrusion molding machine in which a discharge outlet of a twin screw extruder and a material feed opening of a single screw extruder are connected,

wherein a kneading portion of the twin screw extruder occupies from 30 to 70 vol% of the twin screw extruder.

Claim 2 (Original): The process for producing a ceramic sheet according to Claim 1, wherein the connection portion of the discharge outlet of the twin screw extruder and the material feed opening of the single screw extruder is depressurized.

Claim 3 (Currently Amended): The process for producing a ceramic sheet according to Claim 2, wherein [[the]] a degree of vacuum at the connection portion of the discharge outlet of the twin screw extruder and the material feed opening of the single screw extruder is at most 1332.2 Pa.

Claim 4 (Previously Presented): The process for producing a ceramic sheet according to Claim 1, wherein the temperatures of products discharged from the twin screw extruder and the single screw extruder are from 5 to 15°C.

Claim 5 (Cancelled).

Claim 6 (Currently Amended): The process for producing a ceramic sheet according to Claim [[5]] 1, wherein the kneading portion of the twin screw extruder is made of an abrasive resistant material.

Claim 7 (Previously Presented): The process for producing a ceramic sheet according to Claim 1, wherein a structure to hold the screw is provided at an intermediate portion and/or the tip of the screw in the twin screw extruder.

Claim 8 (Previously Presented): The process for producing a ceramic sheet according to Claim 1, wherein a pressure-equalizing can having a length the same as or longer than its diameter is provided in the single screw extruder.

Claim 9 (Currently Amended): The process for producing a ceramic sheet according to Claim 1, wherein a die having a flat portion with a length of at [[lest]] least 5 mm is provided at a discharge outlet of the single screw extruder.

Claim 10 (Previously Presented): The process for producing a ceramic sheet according to Claim 1, wherein a baffle board is provided between the die at the discharge outlet and the pressure-equalizing can in the single screw extruder.

Claim 11 (Previously Presented): The process for producing a ceramic sheet according to Claim 1, which comprises (a) supplying a powder mixture comprising a ceramic powder, a sintering aid and an organic binder powder through a powder feed portion of the twin screw extruder, (b) supplying a liquid comprising a liquid organic binder, a mold release agent and a plasticizer through a liquid feed portion of the twin screw extruder, (c) kneading

the powder mixture and the liquid in the kneading portion in the interior of the twin screw extruder, and (d) molding a sheet from the single screw extruder equipped with a sheet die.

Claim 12 (Original): The process for producing a ceramic sheet according to Claim 11, wherein the ceramic powder is a nitride ceramic, the sintering aid powder is a rare earth oxide, the organic binder powder is a cellulose or acrylic binder, and the liquid organic binder is an acrylic binder.

Claim 13 (Original): The process for producing a ceramic sheet according to Claim 12, wherein the nitride ceramic is aluminum nitride, and the sheet has an apparent density of at least 2.5 g/cm^3 .

Claim 14 (Previously Presented): The process for producing a ceramic sheet according to Claim 1, wherein the sheet strength is at least 1.47 MPa.

Claim 15 (Withdrawn): A ceramic substrate obtained by applying debinding and sintering treatments to a ceramic sheet produced by the process as defined in Claim 1.

Claim 16 (Withdrawn): The ceramic substrate according to Claim 15, wherein the proportion of void is at most 3 vol%.

Claim 17 (Withdrawn): A ceramic circuit board for a module, which comprises a metal circuit formed on one main surface of the ceramic substrate as defined in Claim 15 and a heatsink joined to the other main surface.

Claim 18 (Withdrawn): The ceramic circuit board for a module according to Claim 17, wherein the 10 pC or higher partial discharge inception voltage is at least 5 kV.

Claim 19 (Withdrawn): A module comprising the ceramic circuit board as defined in Claim 17.